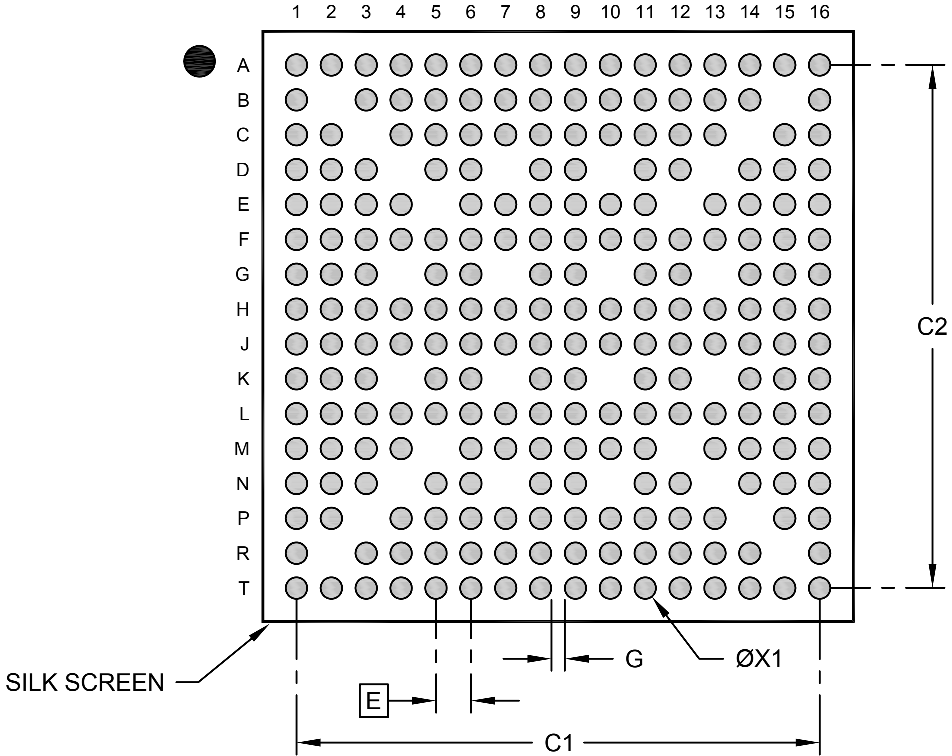
228-Ball Thin, Fine Pitch Ball Grid Array (DWB) - 11x11 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C1		9.75	
Contact Pad Spacing	C2		9.75	
Contact Pad Diameter (X228)	X1			0.42
Contact Pad to Contact Pad	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.